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Conc'd*

an electrically conductive leadframe having a central semiconductor die-receiving region and a plurality of [lead frame] leadframe leads extending outwardly from said central die-receiving region;

a stabilizer extending partially along the length of and on each side of said [lead frame] leadframe leads to improve leadframe planarity; and

a die pad mount integral with and forming a part of said stabilizer disposed beneath said central semiconductor die-receiving region for retaining a semiconductor die thereon.

Claims 2 to 4, line 2 of each, after "stabilizer" add --and die pad mount--

Amend claim 6 as follows:

A2
6. (Amended) A leadframe stabilizer for use with semiconductor devices, comprising:

an electrically conductive leadframe having a central semiconductor die-receiving region and a plurality of [lead frame] leadframe leads extending outwardly from said central die-receiving region;

a stabilizer extending partially along the length of and on each side of said lead [frame] leadframe leads to improve leadframe planarity;

a die pad mount integral with and forming a part of said stabilizer disposed beneath said central semiconductor die-receiving region for retaining a semiconductor die thereon; [and]

a recess in one surface of [the] said die pad mount; and

[into which] a semiconductor die [is] mounted in said recess.

Amend claim 10 as follows:

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10. (Amended) A method for stabilizing the leads of a lead frame and providing a semiconductor die mount pad, comprising the steps of:

providing a leadframe having a central semiconductor die-receiving region and a plurality of leadframe leads extending outwardly from said central die-receiving region;
[molding] adhering a stabilizer [fingers] along part of the length and on each side of [the] said leadframe [lead frame] leads to improve leadframe planarity; and
[molding] forming a die pad integral with [the] said stabilizer [fingers] disposed beneath said central semiconductor die-receiving region.

Claim 11, line 3, after "die" add --in said recessed area--.

REMARKS

Claims 1 to 4, 6, 10 and 11 have been amended for clarity and accuracy. Claims 1 to 14 remain active in this application.

The specification and claims have been corrected, where appropriate.

Claims 1, 2, 5 to 7 and 10 to 12 were rejected under 35 U.S.C. 102(e) as being anticipated by Mosely et al. (U.S. 5,824,950). The rejection is respectfully traversed.

Claim 1, from which claims 2 and 5 depend, requires, among other features, a stabilizer extending partially along the length of and on each side of the leadframe leads and a die pad mount integral with and forming a part of the stabilizer disposed beneath the central semiconductor die-receiving region for retaining a semiconductor die thereon. No such structure is taught or suggested by Mosely et al. Note that the alleged stabilizer